# 1-Kb, 2-Kb, 4-Kb, 8-Kb and 16-Kb I<sup>2</sup>C CMOS Serial EEPROM

### Description

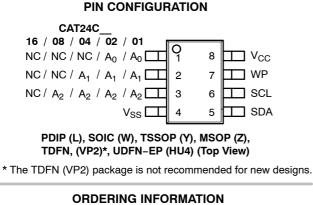
The CAT24C01/02/04/08/16 are 1–Kb, 2–Kb, 4–Kb, 8–Kb and 16–Kb respectively CMOS Serial EEPROM devices organized internally as 8/16/32/64 and 128 pages respectively of 16 bytes each. All devices support both the Standard (100 kHz) as well as Fast (400 kHz) I<sup>2</sup>C protocol.

Data is written by providing a starting address, then loading 1 to 16 contiguous bytes into a Page Write Buffer, and then writing all data to non-volatile memory in one internal write cycle. Data is read by providing a starting address and then shifting out data serially while automatically incrementing the internal address count.

External address pins make it possible to address up to eight CAT24C01 or CAT24C02, four CAT24C04, two CAT24C08 and one CAT24C16 device on the same bus.

#### Features

- Supports Standard and Fast I<sup>2</sup>C Protocol
- 1.7 V to 5.5 V Supply Voltage Range
- 16-Byte Page Write Buffer
- Hardware Write Protection for Entire Memory
- Schmitt Triggers and Noise Suppression Filters on I<sup>2</sup>C Bus Inputs (SCL and SDA)
- Low power CMOS Technology
- More than 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Industrial and Extended Temperature Range
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

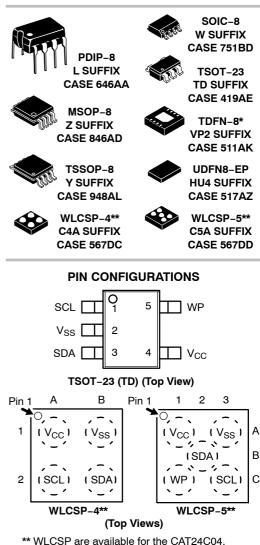


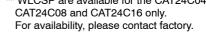
See detailed ordering and shipping information in the package dimensions section on page 18 of this data sheet.

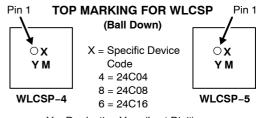


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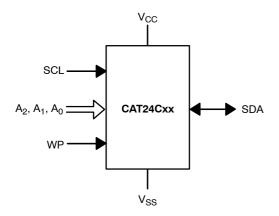
http://onsemi.com







Y = Production Year (Last Digit) M = Production Month (1–9, O, N, D)



### Figure 1. Functional Symbol

#### Table 1. PIN FUNCTION

Pin Name <sup>†</sup>	Function	
A0, A1, A2	Device Address Input	
SDA	Serial Data Input/Output	
SCL	Serial Clock Input	
WP	Write Protect Input	
V <sub>CC</sub>	Power Supply	
V <sub>SS</sub>	Ground	
NC	No Connect	

†The exposed pad for the TDFN/UDFN packages can be left floating or connected to Ground.

#### Table 2. ABSOLUTE MAXIMUM RATINGS

Parameters	Ratings	Units
Storage Temperature	–65 to +150	°C
Voltage on any pin with respect to Ground (Note 1)	–0.5 to +6.5	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

During input transitions, voltage undershoot on any pin should not exceed –1 V for more than 20 ns. Voltage overshoot on pins A<sub>0</sub>, A<sub>1</sub>, A<sub>2</sub> and WP should not exceed V<sub>CC</sub> + 1 V for more than 20 ns, while voltage on the I<sup>2</sup>C bus pins, SCL and SDA, should not exceed the absolute maximum ratings, irrespective of V<sub>CC</sub>.

#### Table 3. RELIABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
N <sub>END</sub> (Note 3)	Endurance	1,000,000	Program / Erase Cycles
T <sub>DR</sub>	Data Retention	100	Years

2. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

3. Page Mode, V<sub>CC</sub> = 5 V, 25°C.

### Table 4. D.C. OPERATING CHARACTERISTICS

 $(V_{CC}$  = 1.8 V to 5.5 V,  $T_A$  = -40°C to +125°C and  $V_{CC}$  = 1.7 V to 5.5 V,  $T_A$  = -40°C to +85°C, unless otherwise specified.)

					• •	
Symbol	Parameter	Test Conc	litions	Min	Мах	Units
I <sub>CCR</sub>	Read Current	Read, f <sub>SCL</sub> = 400 kHz			1	mA
I <sub>CCW</sub>	Write Current	Write, f <sub>SCL</sub> = 400 kHz			2	mA
I <sub>SB</sub>	Standby Current	All I/O Pins at GND or $V_{\mbox{CC}}$	$T_A$ = -40°C to +85°C $V_{CC}$ $\leq$ 3.3 V		1	μA
			$\begin{array}{l} T_{A}=-40^{\circ}C \text{ to } +85^{\circ}C \\ V_{CC}>3.3 \text{ V} \end{array}$		3	
			$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$		5	
١ <sub>L</sub>	I/O Pin Leakage	Pin at GND or $V_{CC}$			2	μA
V <sub>IL</sub>	Input Low Voltage			-0.5	0.3 x V <sub>CC</sub>	V
$V_{\text{IH}}$	Input High Voltage	$A_0$ , $A_1$ , $A_2$ and WP		0.7 x V <sub>CC</sub>	V <sub>CC</sub> + 0.5	V
		SCL and SDA		0.7 x V <sub>CC</sub>	5.5	
V <sub>OL</sub> Output Low	$V_{CC}$ > 2.5 V, $I_{OL}$ = 3 mA			0.4		
	Voltage	$V_{CC}$ < 2.5 V, $I_{OL}$ = 1 mA			0.2	

#### Table 5. PIN IMPEDANCE CHARACTERISTICS

(V<sub>CC</sub> = 1.8 V to 5.5 V,  $T_A = -40^{\circ}$ C to +125°C and V<sub>CC</sub> = 1.7 V to 5.5 V,  $T_A = -40^{\circ}$ C to +85°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Max	Units
C <sub>IN</sub> (Note 4)	SDA Pin Capacitance	$V_{IN}$ = 0 V, f = 1.0 MHz, $V_{CC}$ = 5.0 V	8	pF
	Other Pins		6	pF
I <sub>WP</sub> (Note 5)	WP Input Current	$V_{IN} < V_{IH}, V_{CC} = 5.5 V$	130	μΑ
		$V_{IN} < V_{IH}, V_{CC} = 3.3 V$	120	
		$V_{IN} < V_{IH}, V_{CC} = 1.7 V$	80	
		$V_{IN} > V_{IH}$	2	
I <sub>A</sub> (Note 5)	Address Input Current	$V_{IN} < V_{IH}, V_{CC} = 5.5 V$	50	μΑ
Product Rev	(A0, A1, A2) Product Rev H: CAT24C02	$V_{IN} < V_{IH}, V_{CC} = 3.3 V$	35	
	Product Rev K: CAT24C04, CAT24C08, CAT24C16	$V_{IN} < V_{IH}, V_{CC} = 1.7 V$	25	
	,	$V_{IN} > V_{IH}$	2	

4. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

5. When not driven, the WP, A0, A1 and A2 pins are pulled down to GND internally. For improved noise immunity, the internal pull-down is relatively strong; therefore the external driver must be able to supply the pull-down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer (~ 0.5 x VCC), the strong pull-down reverts to a weak current source.

#### Table 6. A.C. CHARACTERISTICS

(Note 6) (V<sub>CC</sub> = 1.8 V to 5.5 V,  $T_A = -40^{\circ}$ C to +125°C and  $V_{CC} = 1.7$  V to 5.5 V,  $T_A = -40^{\circ}$ C to +85°C, unless otherwise specified.)

		Star	dard	Fa	ist	
Symbol	Parameter	Min	Max	Min	Max	Units
F <sub>SCL</sub>	Clock Frequency		100		400	kHz
t <sub>HD:STA</sub>	START Condition Hold Time	4		0.6		μs
t <sub>LOW</sub>	Low Period of SCL Clock	4.7		1.3		μs
tHIGH	High Period of SCL Clock	4		0.6		μs
t <sub>SU:STA</sub>	START Condition Setup Time	4.7		0.6		μs
t <sub>HD:DAT</sub>	Data In Hold Time	0		0		μs
t <sub>SU:DAT</sub>	Data In Setup Time	250		100		ns
t <sub>R</sub>	SDA and SCL Rise Time		1000		300	ns
t <sub>F</sub> (Note 6)	SDA and SCL Fall Time		300		300	ns
t <sub>SU:STO</sub>	STOP Condition Setup Time	4		0.6		μs
t <sub>BUF</sub>	Bus Free Time Between STOP and START	4.7		1.3		μs
t <sub>AA</sub>	SCL Low to Data Out Valid		3.5		0.9	μs
t <sub>DH</sub>	Data Out Hold Time	100		100		ns
T <sub>i</sub> (Note 6)	Noise Pulse Filtered at SCL and SDA Inputs		100		100	ns
t <sub>SU:WP</sub>	WP Setup Time	0		0		μs
t <sub>HD:WP</sub>	WP Hold Time	2.5		2.5		μs
t <sub>WR</sub>	Write Cycle Time		5		5	ms
t <sub>PU</sub> (Notes 7, 8)	Power-up to Ready Mode		1		1	ms

6. Test conditions according to "AC Test Conditions" table.

7. Tested initially and after a design or process change that affects this parameter.

8.  $t_{PU}$  is the delay between the time V<sub>CC</sub> is stable and the device is ready to accept commands.

Table 7. A.C. TEST CONDITIONS				
Input Drive Levels	0.2 x V <sub>CC</sub> to 0.8 x V <sub>CC</sub>			
Input Rise and Fall Time	≤ 50 ns			
Input Reference Levels	$0.3 \times V_{CC}, 0.7 \times V_{CC}$			
Output Reference Level	0.5 x V <sub>CC</sub>			
Output Test Load	Current Source I_{OL} = 3 mA (V_{CC} $\geq$ 2.5 V); I_{OL} = 1 mA (V_{CC} < 2.5 V); C_L = 100 pF			

#### Table 7. A.C. TEST CONDITIONS

### Power-On Reset (POR)

Each CAT24Cxx\* incorporates Power–On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state.

A CAT24Cxx device will power up into Standby mode after  $V_{CC}$  exceeds the POR trigger level and will power down into Reset mode when  $V_{CC}$  drops below the POR trigger level. This bi-directional POR feature protects the device against 'brown-out' failure following a temporary loss of power.

\*For common features, the CAT24C01/02/04/08/16 will be referred to as CAT24Cxx.

### **Pin Description**

**SCL**: The Serial Clock input pin accepts the Serial Clock generated by the Master.

**SDA**: The Serial Data I/O pin receives input data and transmits data stored in EEPROM. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and is delivered on the negative edge of SCL.

**A0, A1 and A2**: The Address inputs set the device address when cascading multiple devices. When not driven, these pins are pulled LOW internally.

**WP**: The Write Protect input pin inhibits all write operations, when pulled HIGH. When not driven, this pin is pulled LOW internally.

### **Functional Description**

The CAT24Cxx supports the Inter–Integrated Circuit  $(I^{2}C)$  Bus data transmission protocol, which defines a device that sends data to the bus as a transmitter and a device receiving data as a receiver. Data flow is controlled by a Master device, which generates the serial clock and all START and STOP conditions. The CAT24Cxx acts as a Slave device. Master and Slave alternate as either transmitter or receiver.

### I<sup>2</sup>C Bus Protocol

The I<sup>2</sup>C bus consists of two 'wires', SCL and SDA. The two wires are connected to the  $V_{CC}$  supply via pull-up resistors. Master and Slave devices connect to the 2-wire

bus via their respective SCL and SDA pins. The transmitting device pulls down the SDA line to 'transmit' a '0' and releases it to 'transmit' a '1'.

Data transfer may be initiated only when the bus is not busy (see AC Characteristics).

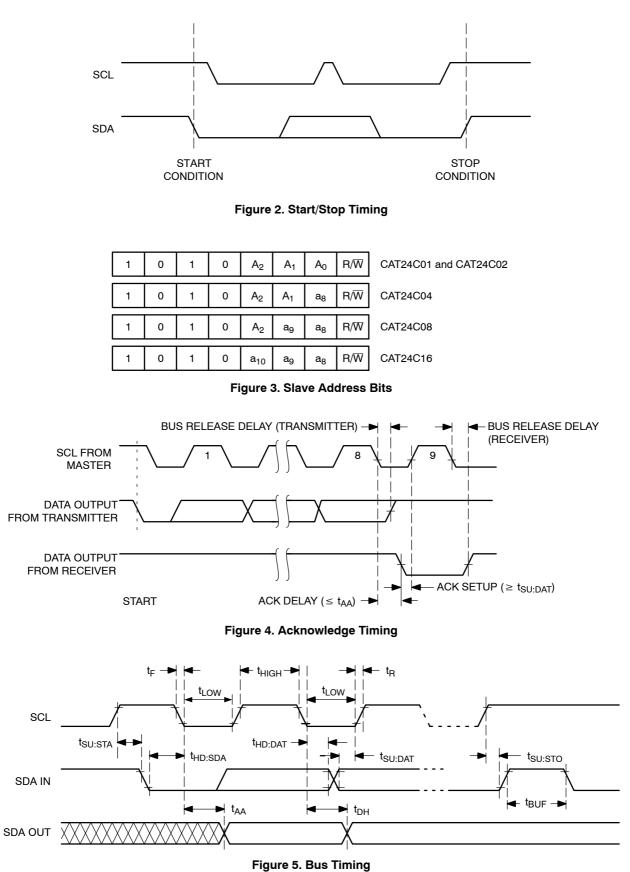
During data transfer, the SDA line must remain stable while the SCL line is high. An SDA transition while SCL is high will be interpreted as a START or STOP condition (Figure 2). The START condition precedes all commands. It consists of a HIGH to LOW transition on SDA while SCL is HIGH. The START acts as a 'wake–up' call to all receivers. Absent a START, a Slave will not respond to commands. The STOP condition completes all commands. It consists of a LOW to HIGH transition on SDA while SCL is HIGH.

### **Device Addressing**

The Master initiates data transfer by creating a START condition on the bus. The Master then broadcasts an 8-bit serial Slave address. For normal Read/Write operations, the first 4 bits of the Slave address are fixed at 1010 (Ah). The next 3 bits are used as programmable address bits when cascading multiple devices and/or as internal address bits. The last bit of the slave address, R/W, specifies whether a Read (1) or Write (0) operation is to be performed. The 3 address space extension bits are assigned as illustrated in Figure 3. A<sub>2</sub>, A<sub>1</sub> and A<sub>0</sub> must match the state of the external address pins, and  $a_{10}$ ,  $a_9$  and  $a_8$  are internal address bits.

### Acknowledge

After processing the Slave address, the Slave responds with an acknowledge (ACK) by pulling down the SDA line during the 9th clock cycle (Figure 4). The Slave will also acknowledge the address byte and every data byte presented in Write mode. In Read mode the Slave shifts out a data byte, and then releases the SDA line during the 9<sup>th</sup> clock cycle. As long as the Master acknowledges the data, the Slave will continue transmitting. The Master terminates the session by not acknowledging the last data byte (NoACK) and by issuing a STOP condition. Bus timing is illustrated in Figure 5.



### WRITE OPERATIONS

### **Byte Write**

In Byte Write mode, the Master sends the START condition and the Slave address with the R/W bit set to zero to the Slave. After the Slave generates an acknowledge, the Master sends the byte address that is to be written into the address pointer of the CAT24Cxx. After receiving another acknowledge from the Slave, the Master transmits the data byte to be written into the addressed memory location. The CAT24Cxx device will acknowledge the data byte and the Master generates the STOP condition, at which time the device begins its internal Write cycle to nonvolatile memory (Figure 6). While this internal cycle is in progress (t<sub>WR</sub>), the SDA output will be tri–stated and the CAT24Cxx will not respond to any request from the Master device (Figure 7).

### Page Write

The CAT24Cxx writes up to 16 bytes of data in a single write cycle, using the Page Write operation (Figure 8). The Page Write operation is initiated in the same manner as the Byte Write operation, however instead of terminating after the data byte is transmitted, the Master is allowed to send up to fifteen additional bytes. After each byte has been transmitted the CAT24Cxx will respond with an acknowledge and internally increments the four low order address bits. The high order bits that define the page address remain unchanged. If the Master transmits more than sixteen bytes prior to sending the STOP condition, the address counter 'wraps around' to the beginning of page and previously transmitted data will be overwritten. Once all

sixteen bytes are received and the STOP condition has been sent by the Master, the internal Write cycle begins. At this point all received data is written to the CAT24Cxx in a single write cycle.

### Acknowledge Polling

The acknowledge (ACK) polling routine can be used to take advantage of the typical write cycle time. Once the stop condition is issued to indicate the end of the host's write operation, the CAT24Cxx initiates the internal write cycle. The ACK polling can be initiated immediately. This involves issuing the start condition followed by the slave address for a write operation. If the CAT24Cxx is still busy with the write operation, NoACK will be returned. If the CAT24Cxx has completed the internal write operation, an ACK will be returned and the host can then proceed with the next read or write operation.

### Hardware Write Protection

With the WP pin held HIGH, the entire memory is protected against Write operations. If the WP pin is left floating or is grounded, it has no impact on the operation of the CAT24Cxx. The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the first data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the CAT24Cxx will not acknowledge the data byte and the Write request will be rejected.

### **Delivery State**

The CAT24Cxx is shipped erased, i.e., all bytes are FFh.

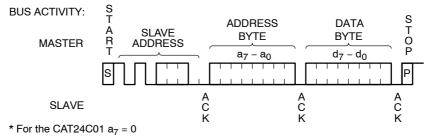
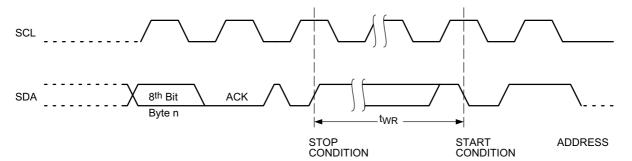
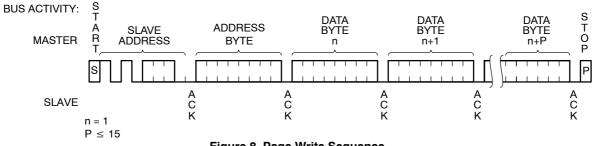


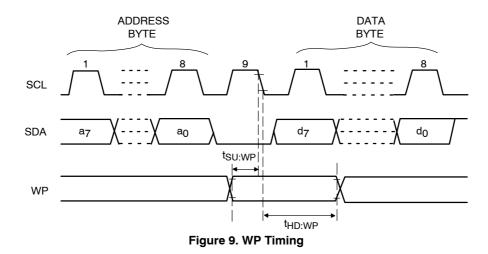
Figure 6. Byte Write Sequence











### **READ OPERATIONS**

#### **Immediate Read**

Upon receiving a Slave address with the R/W bit set to '1', the CAT24Cxx will interpret this as a request for data residing at the current byte address in memory. The CAT24Cxx will acknowledge the Slave address, will immediately shift out the data residing at the current address, and will then wait for the Master to respond. If the Master does not acknowledge the data (NoACK) and then follows up with a STOP condition (Figure 10), the CAT24Cxx returns to Standby mode.

#### **Selective Read**

Selective Read operations allow the Master device to select at random any memory location for a read operation. The Master device first performs a 'dummy' write operation by sending the START condition, slave address and byte address of the location it wishes to read. After the CAT24Cxx acknowledges the byte address, the Master device resends the START condition and the slave address, this time with the R/W bit set to one. The CAT24Cxx then responds with its acknowledge and sends the requested data byte. The Master device does not acknowledge the data (NoACK) but will generate a STOP condition (Figure 11).

#### Sequential Read

If during a Read session, the Master acknowledges the 1<sup>st</sup> data byte, then the CAT24Cxx will continue transmitting data residing at subsequent locations until the Master responds with a NoACK, followed by a STOP (Figure 12). In contrast to Page Write, during Sequential Read the address count will automatically increment to and then wrap–around at end of memory (rather than end of page). In the CAT24C01, the internal address count will not wrap around at the end of the 128 byte memory space.

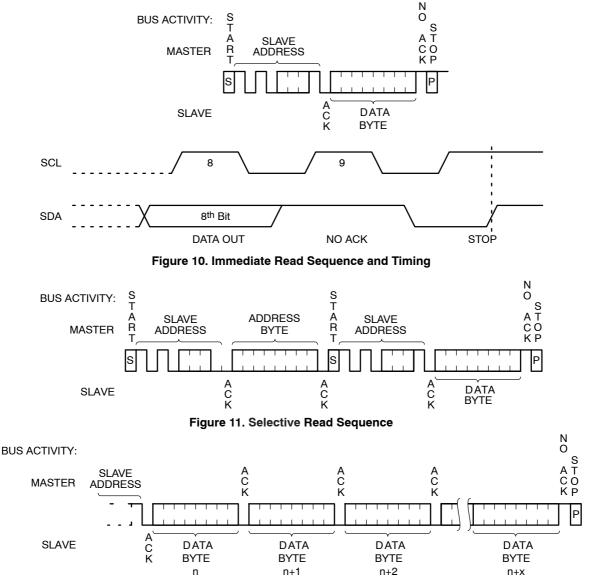
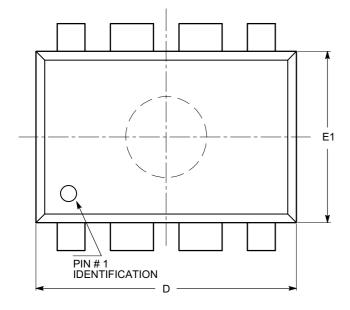


Figure 12. Sequential Read Sequence

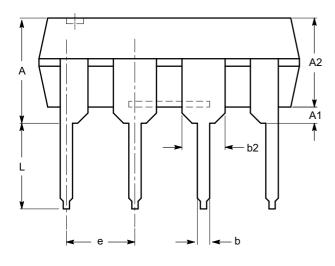
### PACKAGE DIMENSIONS

PDIP-8, 300 mils CASE 646AA ISSUE A



SYMBOL	MIN	NOM	MAX	
А			5.33	
A1	0.38			
A2	2.92	3.30	4.95	
b	0.36	0.46	0.56	
b2	1.14	1.52	1.78	
с	0.20	0.25	0.36	
D	9.02	9.27	10.16	
E	7.62	7.87	8.25	
E1	6.10	6.35	7.11	
е	2.54 BSC			
eB	7.87		10.92	
L	2.92	3.30	3.80	

TOP VIEW

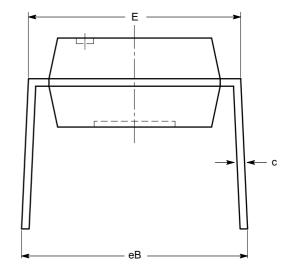


SIDE VIEW

#### Notes:

(1) All dimensions are in millimeters.

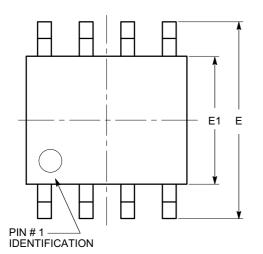
(2) Complies with JEDEC MS-001.



END VIEW

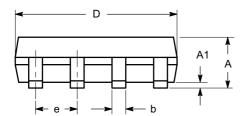
### PACKAGE DIMENSIONS

SOIC 8, 150 mils CASE 751BD ISSUE O



SYMBOL	MIN	NOM	MAX
А	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
с	0.19		0.25
D	4.80		5.00
E	5.80		6.20
E1	3.80		4.00
е		1.27 BSC	
h	0.25		0.50
L	0.40		1.27
θ	0°		8°

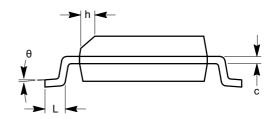
TOP VIEW



SIDE VIEW

#### Notes:

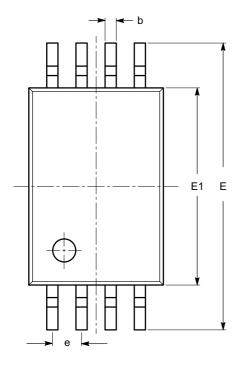
(1) All dimensions are in millimeters. Angles in degrees.(2) Complies with JEDEC MS-012.



END VIEW

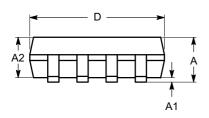
### PACKAGE DIMENSIONS

TSSOP8, 4.4x3 CASE 948AL ISSUE O

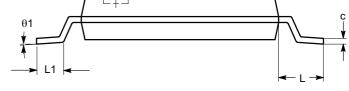


SYMBOL	MIN	NOM	MAX
А			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
с	0.09		0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
е		0.65 BSC	
L		1.00 REF	
L1	0.50	0.60	0.75
θ	0°		8°

#### TOP VIEW



SIDE VIEW



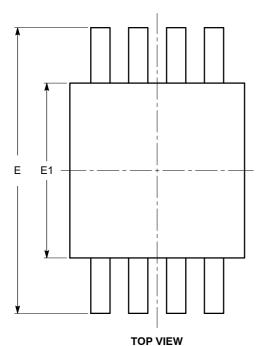
END VIEW

#### Notes:

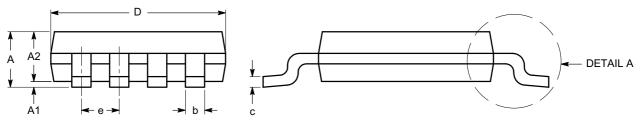
All dimensions are in millimeters. Angles in degrees.
 Complies with JEDEC MO-153.

### PACKAGE DIMENSIONS



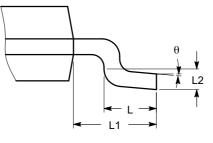


SYMBOL MIN NOM MAX А 1.10 A1 0.05 0.10 0.15 0.75 A2 0.85 0.95 b 0.22 0.38 С 0.13 0.23 D 2.90 3.00 3.10 Е 4.80 4.90 5.00 E1 2.90 3.00 3.10 е 0.65 BSC 0.60 L 0.40 0.80 L1 0.95 REF 0.25 BSC L2 θ 0° 6°



SIDE VIEW





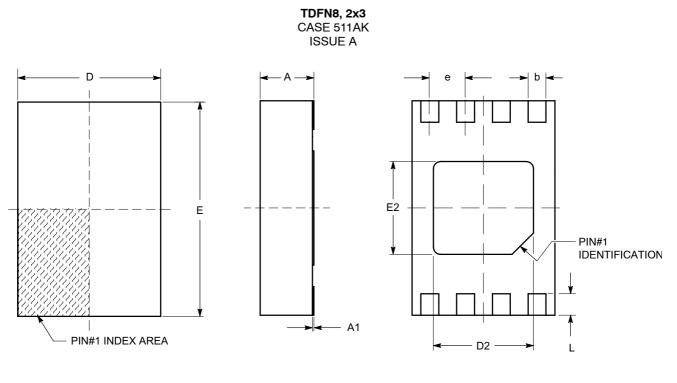


#### Notes:

(1) All dimensions are in millimeters. Angles in degrees.

(2) Complies with JEDEC MO-187.

### PACKAGE DIMENSIONS



TOP VIEW

SIDE VIEW

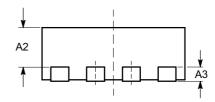
SYMBOL NOM MIN MAX 0.70 0.75 0.80 А A1 0.00 0.02 0.05 A2 0.45 0.55 0.65 A3 0.20 REF 0.25 b 0.20 0.30 D 1.90 2.00 2.10 D2 1.30 1.40 1.50 Е 2.90 3.00 3.10 E2 1.20 1.30 1.40 0.50 TYP е L 0.20 0.30 0.40

Notes:

(1) All dimensions are in millimeters.

(2) Complies with JEDEC MO-229.

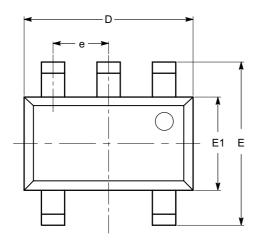
BOTTOM VIEW



FRONT VIEW

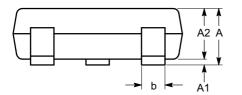
### PACKAGE DIMENSIONS

TSOT-23, 5 LEAD CASE 419AE ISSUE O



SYMBOL	MIN	NOM	MAX
А			1.00
A1	0.01	0.05	0.10
A2	0.80	0.87	0.90
b	0.30		0.45
с	0.12	0.15	0.20
D		2.90 BSC	
E	2.80 BSC		
E1	1.60 BSC		
е		0.95 TYP	
L	0.30	0.40	0.50
L1	0.60 REF		
L2	0.25 BSC		
θ	0°		8°

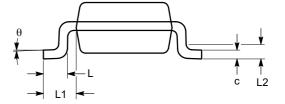
TOP VIEW



SIDE VIEW

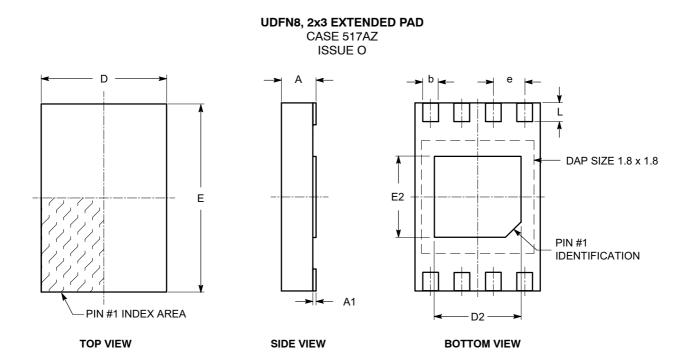
#### Notes:

- All dimensions are in millimeters. Angles in degrees.
  Complies with JEDEC MO-193.



END VIEW

### PACKAGE DIMENSIONS

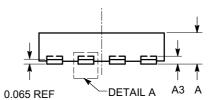


SYMBOL	MIN	NOM	МАХ
А	0.45	0.50	0.55
A1	0.00	0.02	0.05
A3		0.127 REF	
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D2	1.35	1.40	1.45
Е	2.95	3.00	3.05
E2	1.25	1.30	1.35
е	0.50 REF		
L	0.25	0.30	0.35

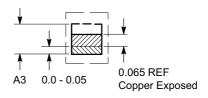
#### Notes:

(1) All dimensions are in millimeters.

(2) Refer JEDEC MO-236/MO-252.

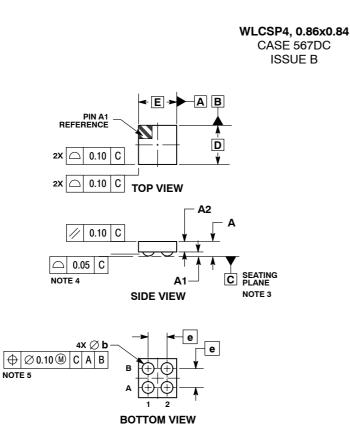






DETAIL A

### PACKAGE DIMENSIONS

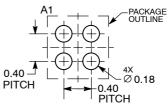


NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME
- DIMENSIONING AND TOLERANCING FER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT DALLS.
- BALLS. 4. COPLANARITY APPLIES TO SPHERICAL CROWNS
- OF THE CONTACT BALLS.
  DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS					
DIM	MIN MAX					
Α	0.28	0.38				
A1	0.08	0.12				
A2	0.23 REF					
b	0.16 0.20					
D	0.86 BSC					
Е	0.84 BSC					
е	0.40 BSC					

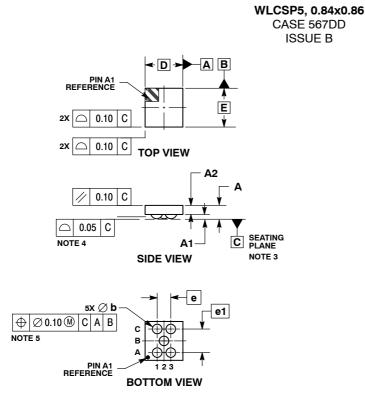
#### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### PACKAGE DIMENSIONS

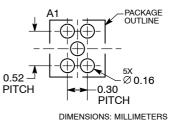


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
  COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
  DIMENSION b IS MEASURED AT THE MAXIMUM CON-TACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS				
DIM	MIN MAX				
Α	0.29	0.39			
A1	0.10	0.10 0.14			
A2	0.23 REF				
b	0.14 0.18				
D	0.84 BSC				
Е	0.86 BSC				
е	0.30 BSC				
e1	0.52	BSC			

#### RECOMMENDED **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **Ordering Information**

### CAT24C01 Ordering Information

Specific Device Marking	Package Type	Temperature Range (Note 9)	Lead Finish	Shipping
MM	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
EE	TDFN-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
24C01WI	SOIC-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
24C01WI	SOIC-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
C01	TSSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
C01	TSSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
ABMK	MSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
	Device Marking        MM        EE        24C01WI        24C01WI        C01        C01	Device Marking      Type        MM      TSOT-23-5        EE      TDFN-8        24C01WI      SOIC-8        24C01WI      SOIC-8        C01      TSSOP-8        C01      TSSOP-8	Device MarkingTypeRange (Note 9)MMTSOT-23-5IndustrialEETDFN-8Industrial24C01WISOIC-8Industrial24C01WISOIC-8ExtendedC01TSSOP-8IndustrialC01TSSOP-8Extended	Device MarkingTypeRange (Note 9)FinishMMTSOT-23-5IndustrialNiPdAuEETDFN-8IndustrialNiPdAu24C01WISOIC-8IndustrialNiPdAu24C01WISOIC-8ExtendedNiPdAuC01TSSOP-8IndustrialNiPdAuC01TSSOP-8ExtendedNiPdAu

### CAT24C02 Ordering Information (Notes 10, 11)

Device Order Number	Specific Device Marking	Package Type	Temperature Range (Note 9)	Lead Finish	Shipping
CAT24C02WI-G	24C02H	SOIC-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C02WI-GA	24C02H	SOIC-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C02WI-GT3	24C02H	SOIC-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02WI-GT3A	24C02H	SOIC-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02WE-GT3	24C02H	SOIC-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02WE-GT3A	24C02H	SOIC-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02YI-G	C02H	TSSOP-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C02YI-GA	C02H	TSSOP-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C02YI-GT3	C02H	TSSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02YI-GT3A	C02H	TSSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02YE-GT3	C02H	TSSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02YE-GT3A	C02H	TSSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02VP2I-GT3*	C1T	TDFN-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02VP2IGT3A*	C1T	TDFN-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02VP2E-GT3*	C1T	TDFN-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02VP2EGT3A*	C1T	TDFN-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02ZI-GT3	C1	MSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02ZE-GT3	C1	MSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02ZI-GT3A	C1	MSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02ZE-GT3A	C1	MSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02TDI-GT3	C1	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02TDE-GT3	C1	TSOT-23-5	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02TDI-GT3A	C1	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02TDE-GT3A	C1	TSOT-23-5	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02LI-GA	24C02H	PDIP-8	Industrial	NiPdAu	Tube, 50 Units / Tube
CAT24C02LE-GA	24C02H	PDIP-8	Extended	NiPdAu	Tube, 50 Units / Tube
CAT24C02HU4IGT3A	C1U	UDFN8-EP	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C02HU4EGT3A	C1U	UDFN8-EP	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel

9. Industrial temperature range is -40°C to +85°C and Extended temperature range is -40°C to +125°C.

10. Part numbers ending with "A" for the CAT24C02 are for Gresham (Product Rev H) only die.

11. The CAT24C02 "non-A" Device Order Numbers use Gresham die (Rev H) for date codes, starting August 1st, 2012. Therefore the Specific Device Marking for these OPNs reflect Rev H die.

\* The TDFN (VP2) package is not recommended for new designs.

### CAT24C04 Ordering Information

Device Order Number	Specific Device Marking	Package Type	Temperature Range (Note 12)	Lead Finish	Shipping
CAT24C04WI-G	24C04K	SOIC-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C04WI-GT3	24C04K	SOIC-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04WE-GT3	24C04K	SOIC-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04YI-G	C04K	TSSOP-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C04YI-GT3	C04K	TSSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04YE-GT3	C04	TSSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04VP2I-GT3*	C2T	TDFN-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04LI-G	24C04K	PDIP-8	Industrial	NiPdAu	Tube, 50 Units / Tube
CAT24C04LE-G	24C04K	PDIP-8	Extended	NiPdAu	Tube, 50 Units / Tube
CAT24C04ZI-GT3	C2	MSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04ZE-GT3	C2	MSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04C4ATR**	4	WLCSP-4	Industrial	N/A	Tape & Reel, 5,000 Units / Reel
CAT24C04C5ATR**	4	WLCSP-5	Industrial	N/A	Tape & Reel, 5,000 Units / Reel
CAT24C04TDI-GT3	C2	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04TDE-GT3	C2	TSOT-23-5	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04HU4I-GT3	C2U	UDFN8-EP	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C04HU4E-GT3	C2U	UDFN8-EP	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel

#### CAT24C08 Ordering Information

Device Order Number	Specific Device Marking	Package Type	Temperature Range (Note 12)	Lead Finish	Shipping
CAT24C08WI-G	24C08K	SOIC-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C08WI-GT3	24C08K	SOIC-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08WE-GT3	24C08K	SOIC-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08YI-G	C08K	TSSOP-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C08YI-GT3	C08K	TSSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08YE-GT3	C08	TSSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08VP2I-GT3*	СЗТ	TDFN-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08VP2E-GT3*	СЗТ	TDFN-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08LI-G	24C08K	PDIP-8	Industrial	NiPdAu	Tube, 50 Units / Tube
CAT24C08LE-G	24C08K	PDIP-8	Extended	NiPdAu	Tube, 50 Units / Tube
CAT24C08ZI-GT3	C3	MSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08ZE-GT3	C3	MSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08C4ATR**	8	WLCSP-4	Industrial	N/A	Tape & Reel, 5,000 Units / Reel
CAT24C08C5ATR**	8	WLCSP-5	Industrial	N/A	Tape & Reel, 5,000 Units / Reel
CAT24C08TDI-GT3	C3	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08TDE-GT3	C3	TSOT-23-5	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08HU4I-GT3	C3U	UDFN8-EP	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C08HU4E-GT3	C3U	UDFN8-EP	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel

12. Industrial temperature range is -40°C to +85°C and Extended temperature range is -40°C to +125°C.

\* The TDFN (VP2) package is not recommended for new designs.

\*\* Contact factory for availability

#### CAT24C16 Ordering Information

Device Order Number	Specific Device Marking	Package Type	Temperature Range (Note 13)	Lead Finish	Shipping
CAT24C16WI-G	24C16K	SOIC-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C16WI-GT3	24C16K	SOIC-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16WE-GT3	24C16K	SOIC-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16YI-G	C16K	TSSOP-8	Industrial	NiPdAu	Tube, 100 Units / Tube
CAT24C16YI-GT3	C16K	TSSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16YE-GT3	C16	TSSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16VP2I-GT3*	C4T	TDFN-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16VP2E-GT3*	C4T	TDFN-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16LI-G	24C16K	PDIP-8	Industrial	NiPdAu	Tube, 50 Units / Tube
CAT24C16LE-G	24C16K	PDIP-8	Extended	NiPdAu	Tube, 50 Units / Tube
CAT24C16ZI-GT3	C4	MSOP-8	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16ZE-GT3	C4	MSOP-8	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16C4ATR**	6	WLCSP-4	Industrial	N/A	Tape & Reel, 5,000 Units / Reel
CAT24C16C5ATR**	6	WLCSP-5	Industrial	N/A	Tape & Reel, 5,000 Units / Reel
CAT24C16TDI-GT3	C4	TSOT-23-5	Industrial	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16TDE-GT3	C4	TSOT-23-5	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24C16HU4I-GT3	C4U	UDFN8-EP	Extended	NiPdAu	Tape & Reel, 3,000 Units / Reel

13. Industrial temperature range is -40°C to +85°C and Extended temperature range is -40°C to +125°C.

14. All packages are RoHS-compliant (Lead-free, Halogen-free).

15. For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

16. For detailed information and a breakdown of device nomenclature and numbering systems, please see the ON Semiconductor Device Nomenclature document, TND310/D, available at <u>www.onsemi.com</u>

\* The TDFN (VP2) package is not recommended for new designs.

\*\* Contact factory for availability

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